

**In the Claims**

**CLAIMS**

Claims 1-30 (Canceled).

31. (New) An engagement probe comprising:  
a semiconductor substrate having an upper surface; and  
a grouping of a plurality of projecting apexes extending upward from the upper surface of the substrate and positioned in sufficient proximity to one another to collectively removably engage a single conductive pad, the projecting apexes are arranged in an interconnecting structure that bounds an area of the upper surface of the semiconductor substrate.

32. (New) The engagement probe of claim 31 wherein the interconnecting structure of the projecting apexes is shaped as a polygon.

33. (New) The engagement probe of claim 31 wherein the area of the upper surface comprises a stop plane.

34. (New) The engagement probe of claim 31 wherein the projecting apexes comprise bulk semiconductor material of the semiconductor substrate.

35. (New) The engagement probe of claim 31 wherein the projecting apexes comprise outermost portions which constitute a first electrically conductive material, and wherein the conductive pad for which the probe is adapted has outermost portions constituting a second electrically conductive material; the first and second electrically conductive materials being different.

36. (New) The engagement probe of claim 31 wherein the projecting apexes are in the shape of multiple knife-edge lines.

37. (New) The engagement probe of claim 31 wherein the projecting apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form the interconnecting structure comprising at least one polygon.

38. (New) The engagement probe of claim 31 wherein the projecting apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form the interconnecting structure comprising at least two polygons one of which is received entirely within the other.

39. (New) The engagement probe of claim 31 wherein the grouping of the plurality of the projecting apexes is formed on a projection extending from a substrate.

40. (New) The engagement probe of claim 31 wherein the projecting apexes have a selected projecting distance, the projecting distance being about one-half the thickness of the conductive pad which the apparatus is adapted to engage.

41. (New) The engagement probe of claim 31 wherein the projecting apexes project from a common plane, the projecting apexes having respective tips and bases, the bases of adjacent projecting apexes being spaced from one another to define a penetration stop plane therebetween.